

高纯锗CMOS-ASIC电子学 研究进展

邓智 何力 刘丰 郝嘉俊 叶祥珂

清华大学-工程物理系

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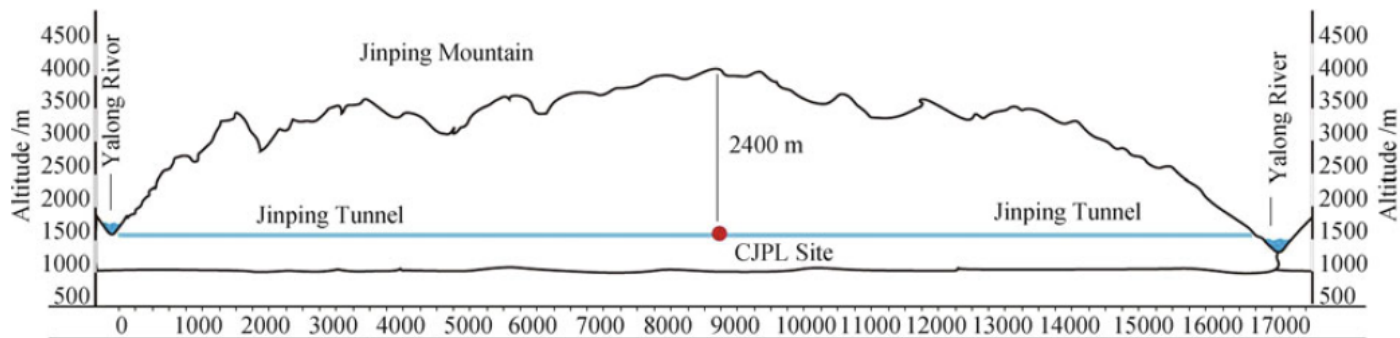
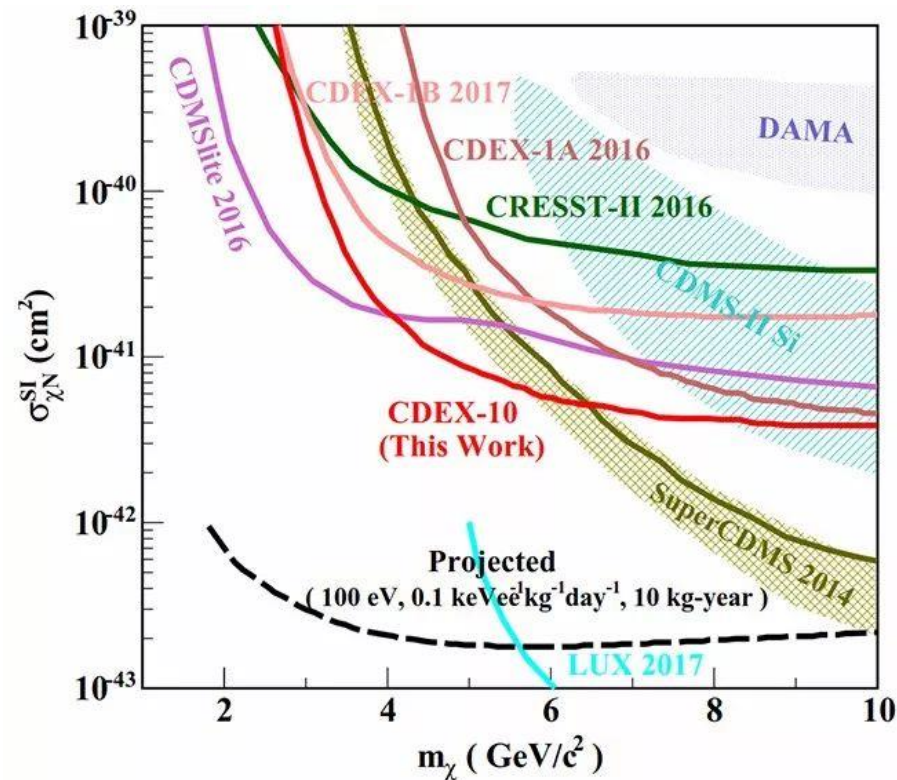
概要

- 背景
- 研究进展：
 - 低温MOS晶体管模型
 - 低温低噪声、宽动态CMOS前放ASIC
 - 低温SCA波形采样ASIC
- 小结

背景

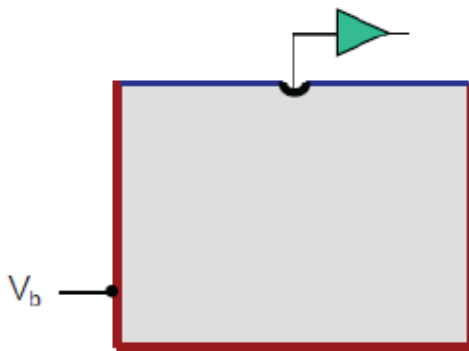
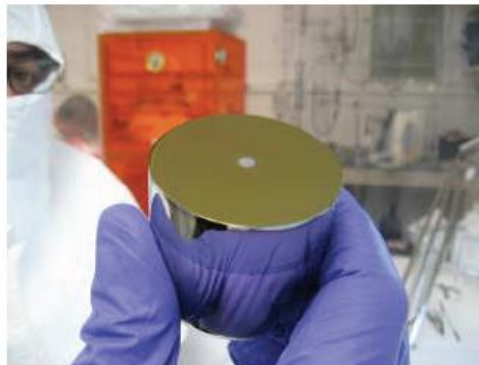
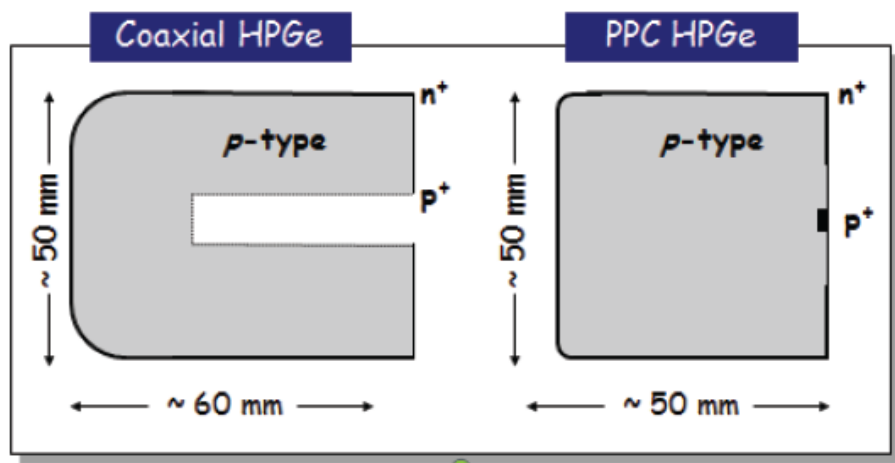
- CDEX实验

- 在锦屏地下实验室开展的基于高纯锗探测器的直接暗物质探测实验
- CDEX1→CDEX10→CDEX100/200



点电极高纯锗探测器

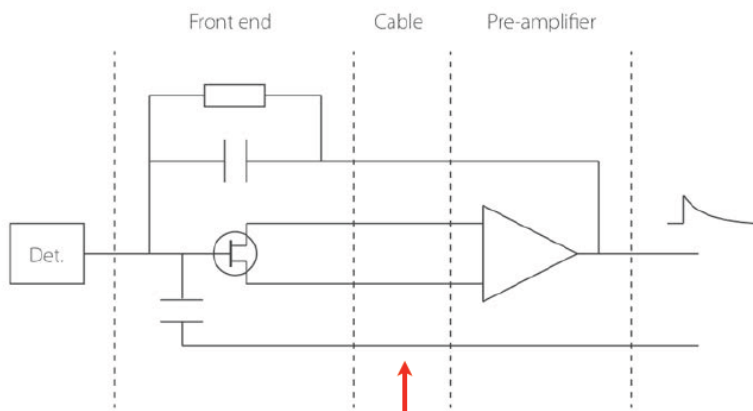
- 采用点电极收集电荷，可实现大体积、小电容，从而降低暗物质探测阈值
- 暗物质和0vbb探测实验：
 - Cogent, CDEX
 - GERDA, MAJORANA, LEGEND



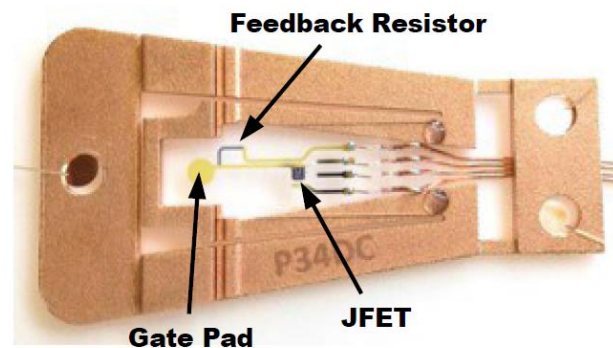
~1pF for 1kg crystal

高纯锗探测器的读出

- 低能量阈值 → 低噪声
- 低本底 → 低质量和“干净”的材料
- 直接浸泡在液氮中 → 工作在77K低温
- 同时探测暗物质和0vbb → 宽动态范围
- 通常高纯锗探测器采用具有较低的1/f噪声的JFET读出



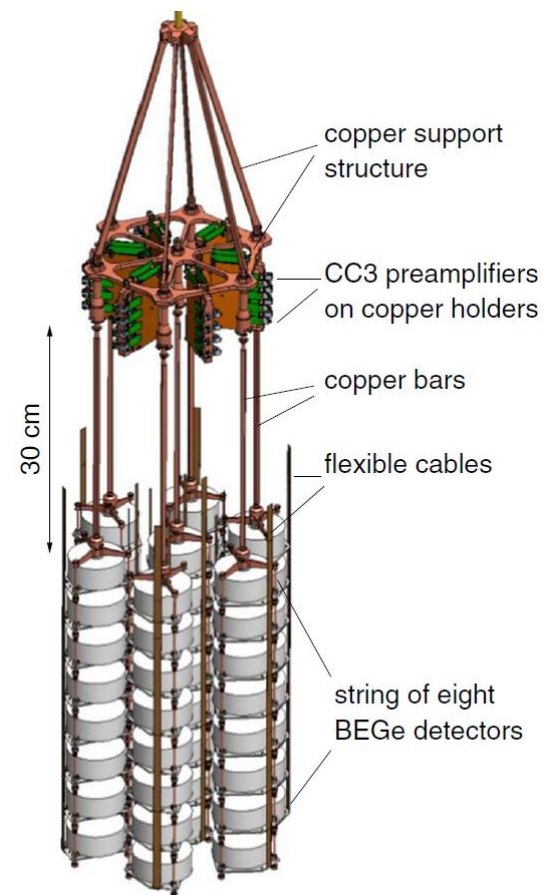
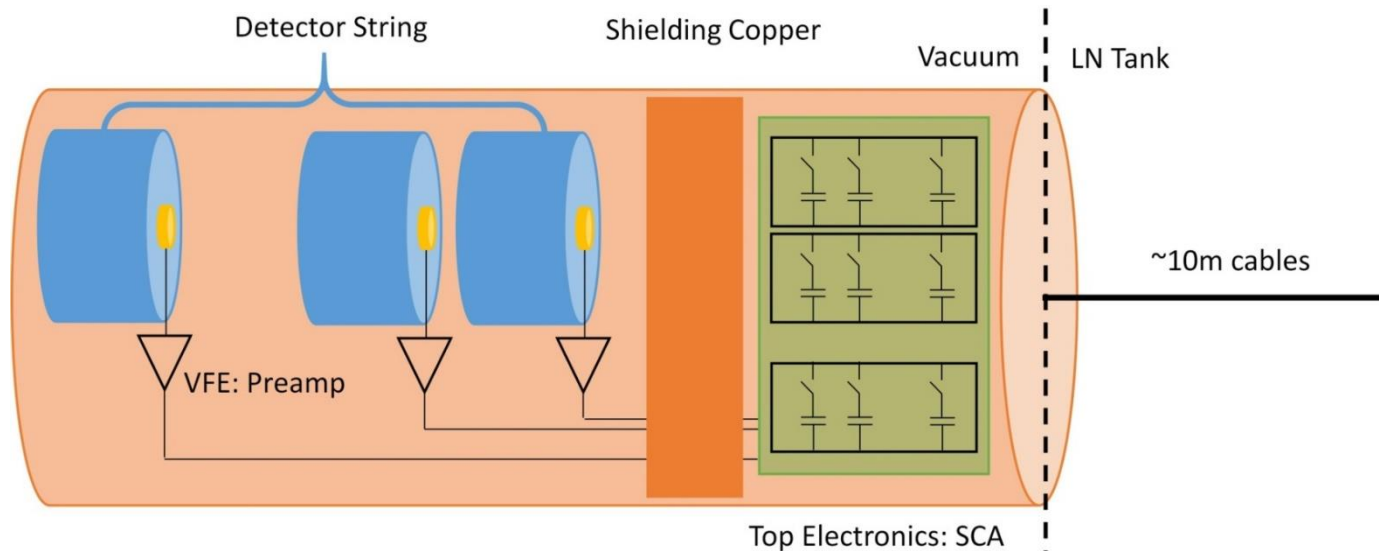
~1m, increases as detector array scales



MAJORANA Demonstrator

高纯锗探测器的读出

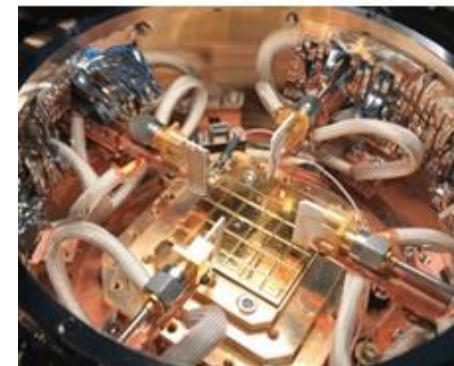
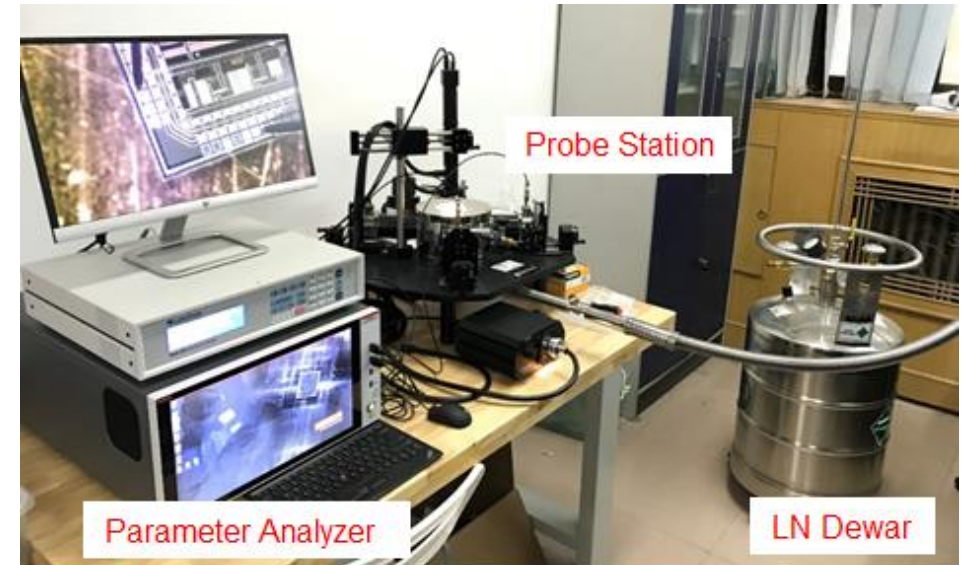
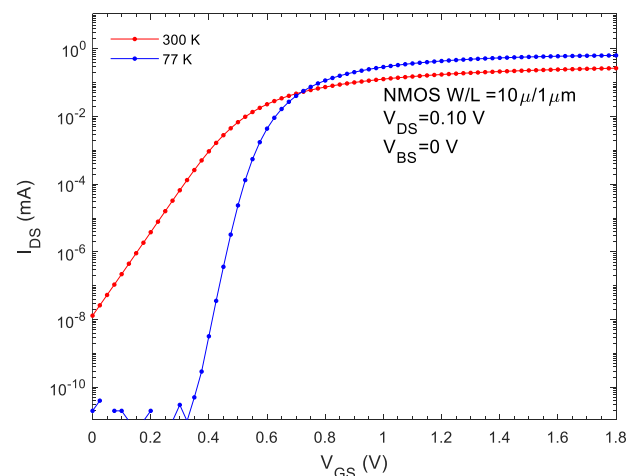
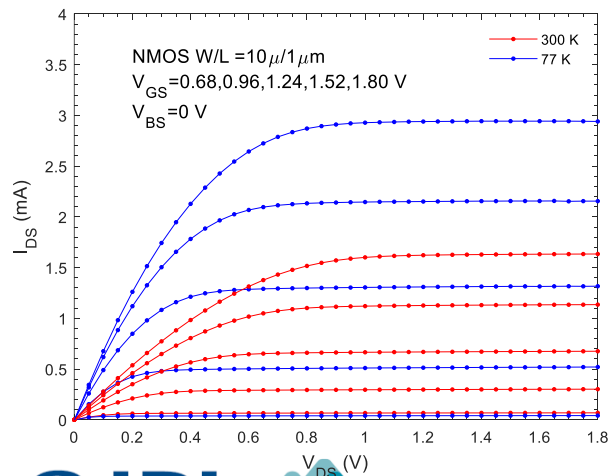
- CMOS ASIC具有集成度高、可定制化等特点，并且可以直接浸泡在液氮中，适合大规模阵列实验
- 基于CMOS ASIC的低温读出电子学方案



低温MOS晶体管模型

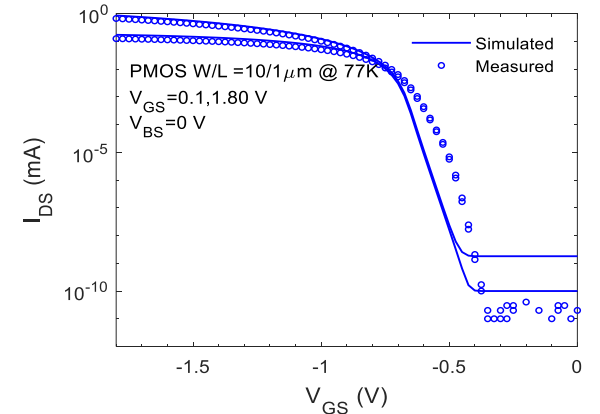
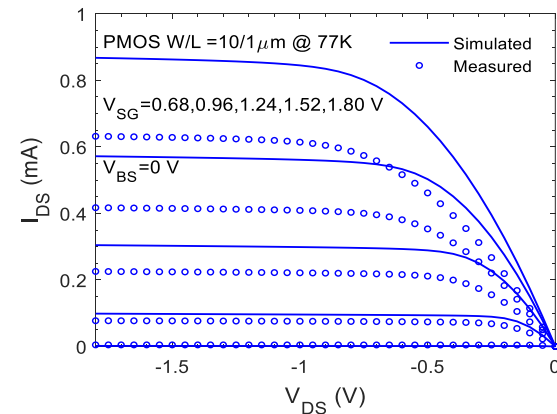
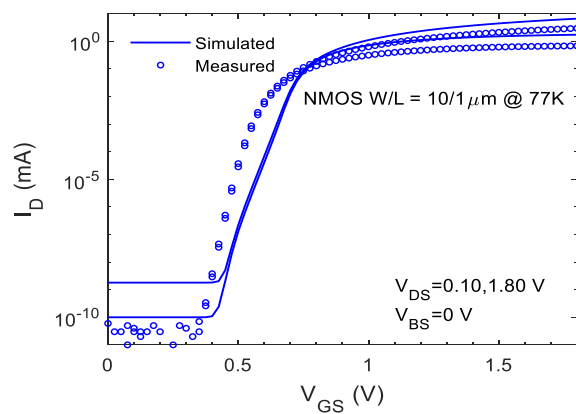
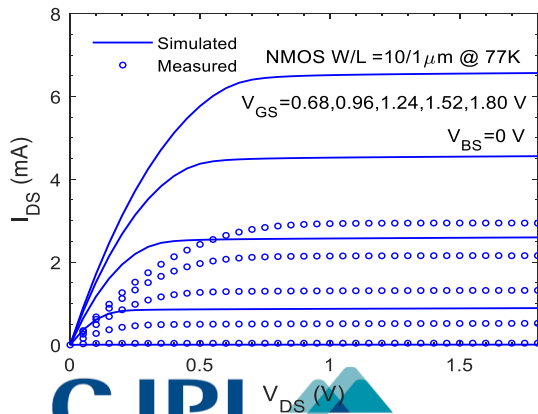
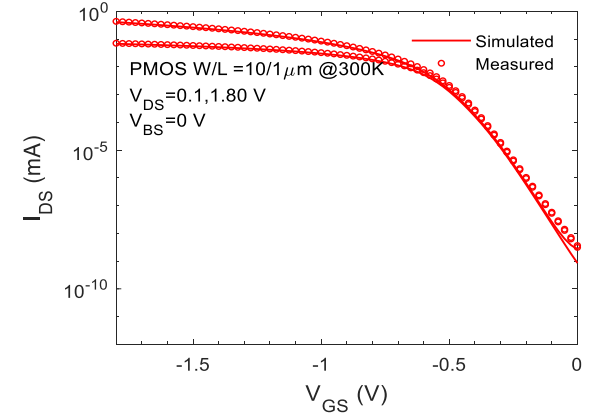
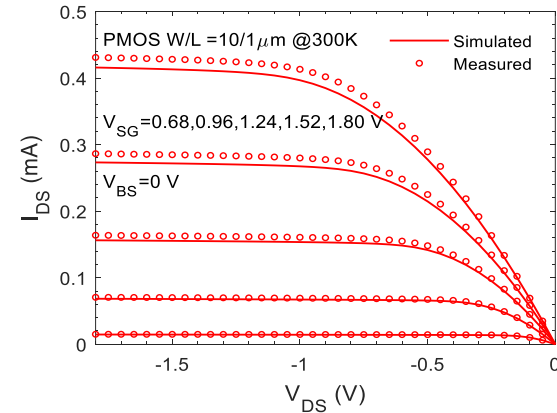
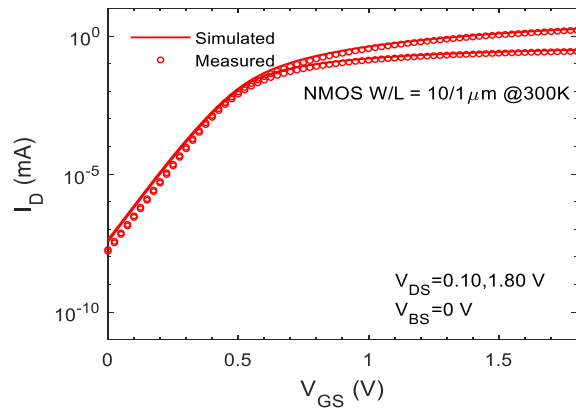
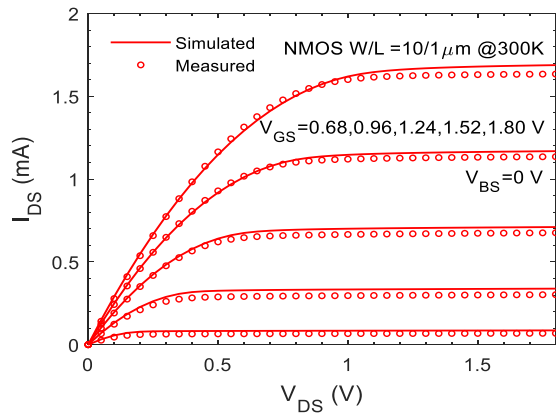
- 低温晶体管I/V测试

TYPE	Parameter
Process	GF 0.18 μm CMOS
Temperature	77 K, 300 K
<i>n</i> - and <i>p</i> -channel MOSFETs	10 μm / 1 μm
	10 μm / 10 μm
	10 μm / 0.35 μm
	0.22 μm / 10 μm



低温MOS晶体管模型

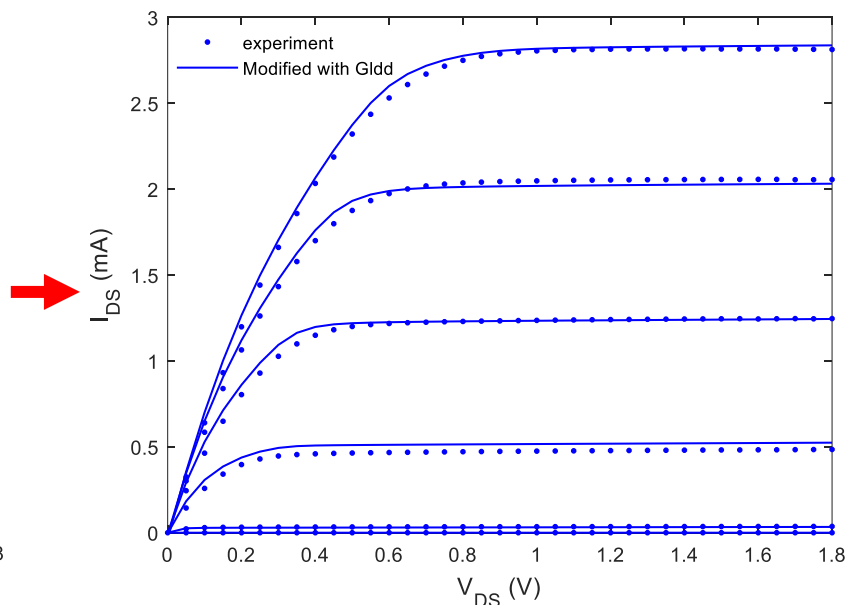
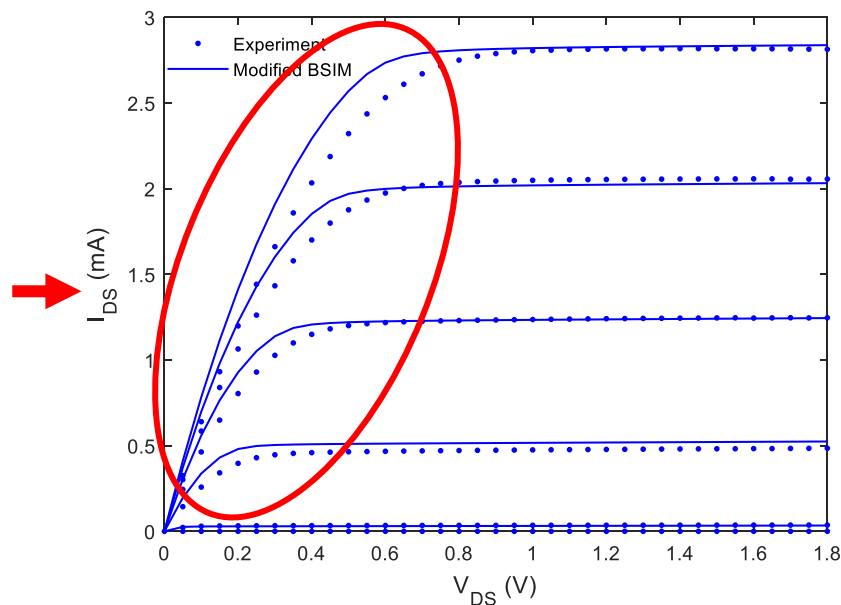
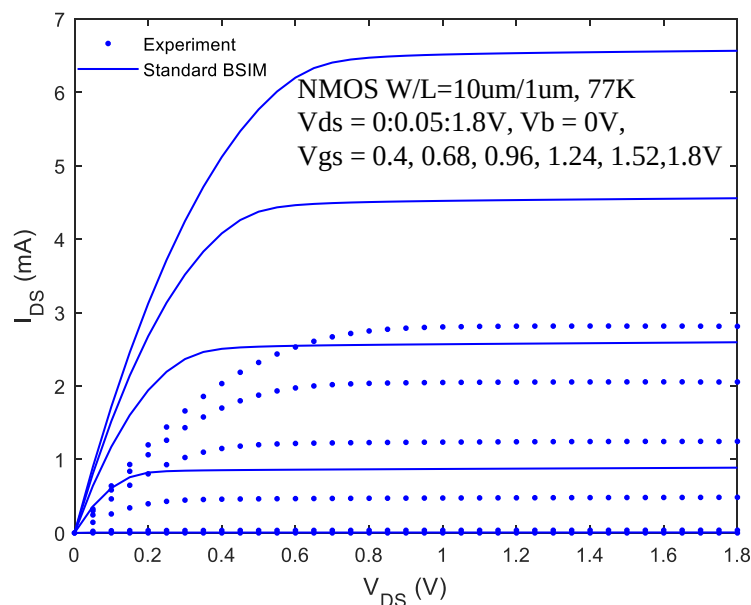
- 标准BSIM模型只适用于220K以上的温度



低温MOS晶体管模型

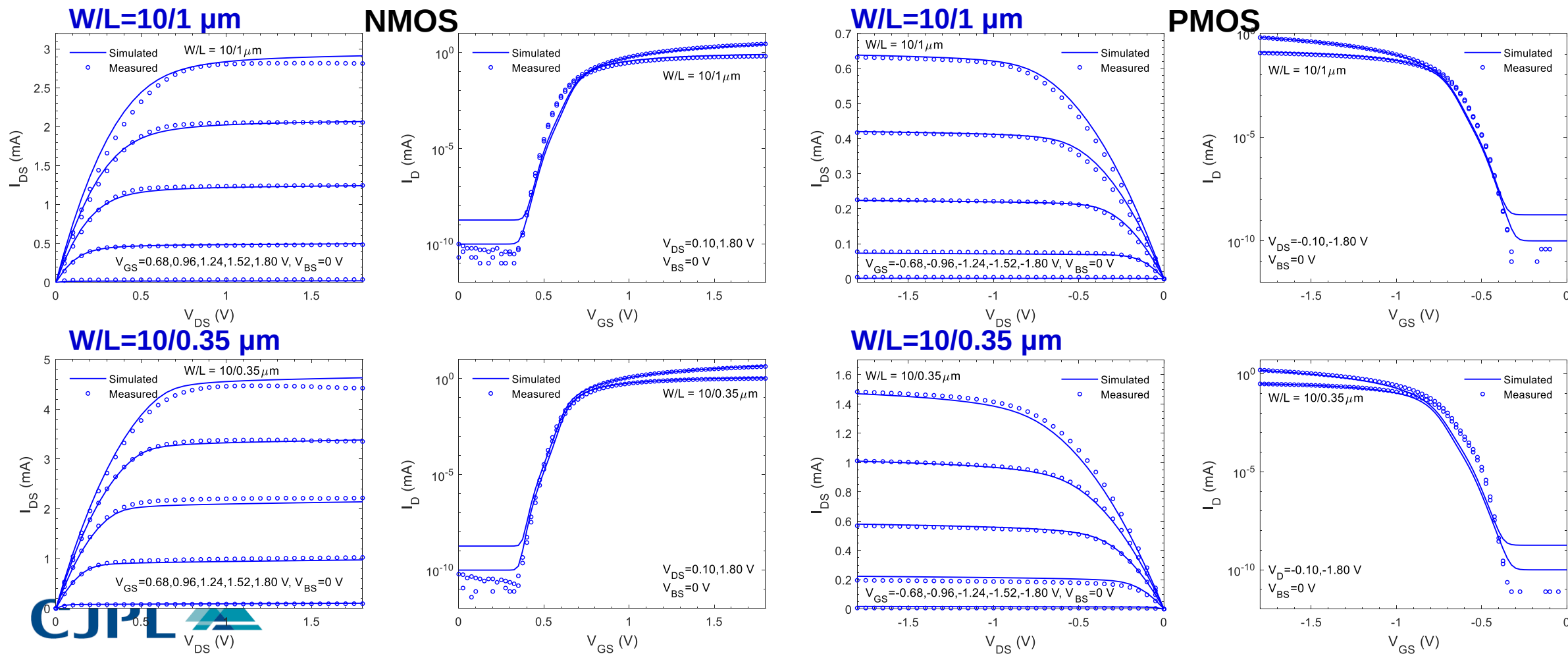
- 通过微调BSIM模型中阈值 (k_{t1})、迁移率 (μ_{te})、饱和速度 (v_{at}) 等参数
- 迭代得到最小误差

$$error = \sqrt{\frac{1}{N} \sum_{i=1}^N \left(\frac{I_{dsim} - I_{dmea}}{I_{dmea}} \right)^2} \times 100\%$$

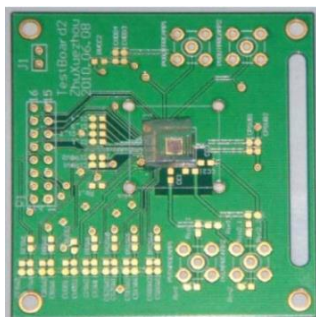
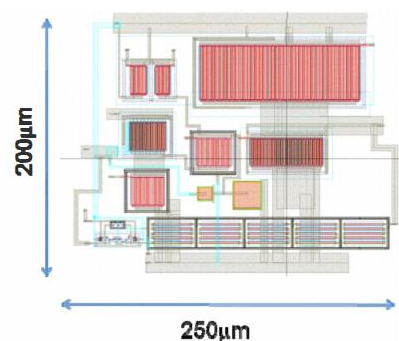


低温MOS晶体管模型

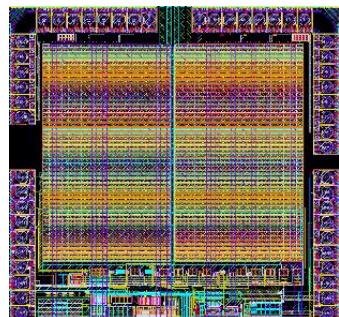
- 修改模型参数后不同尺寸晶体管的IV曲线，仿真与实测值误差<10%



低噪声CMOS前放ASIC



工艺	GF 350nm
ENC	6.5 e ⁻ @ 213K 12μs
能量分辨率	3.9 keV @ 662 keV



工艺	XFAB 350nm
ENC	8.9 e ⁻ @ 77K 12μs
能量分辨率	600 eV @ 122 keV

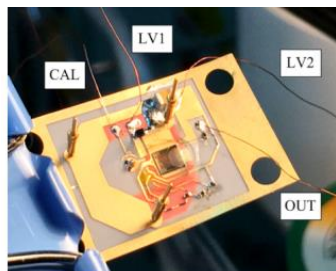
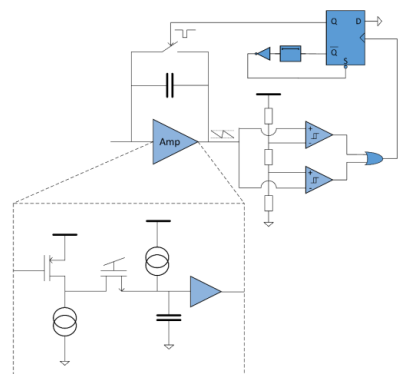
2011

2018

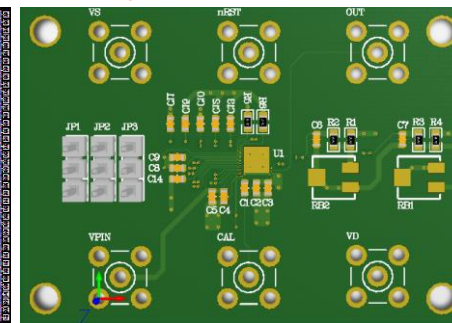
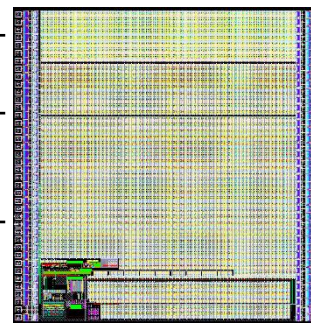
2021

2022

最新版正在测试



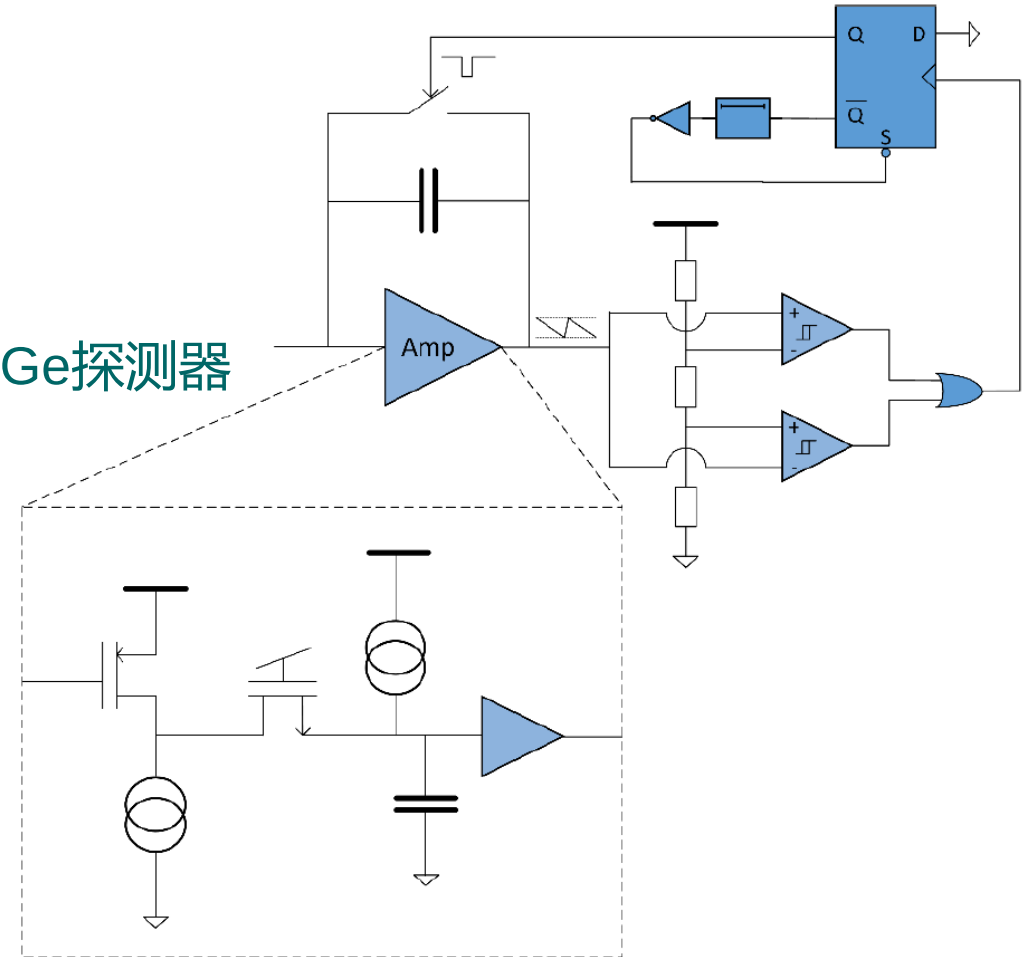
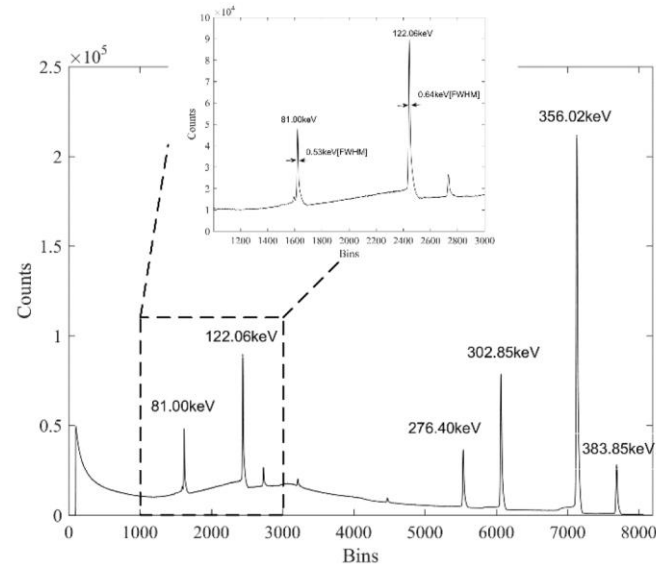
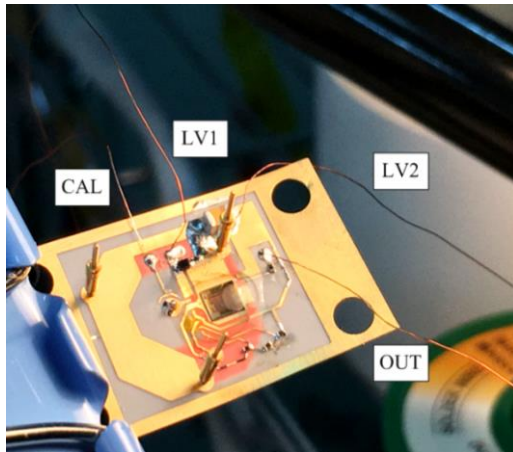
工艺	GF 350nm
ENC	9.7 e ⁻ @ 77K 12μs
能量分辨率	640 eV @ 122 keV



工艺	GF 180nm
ENC	待测
能量分辨率	待测

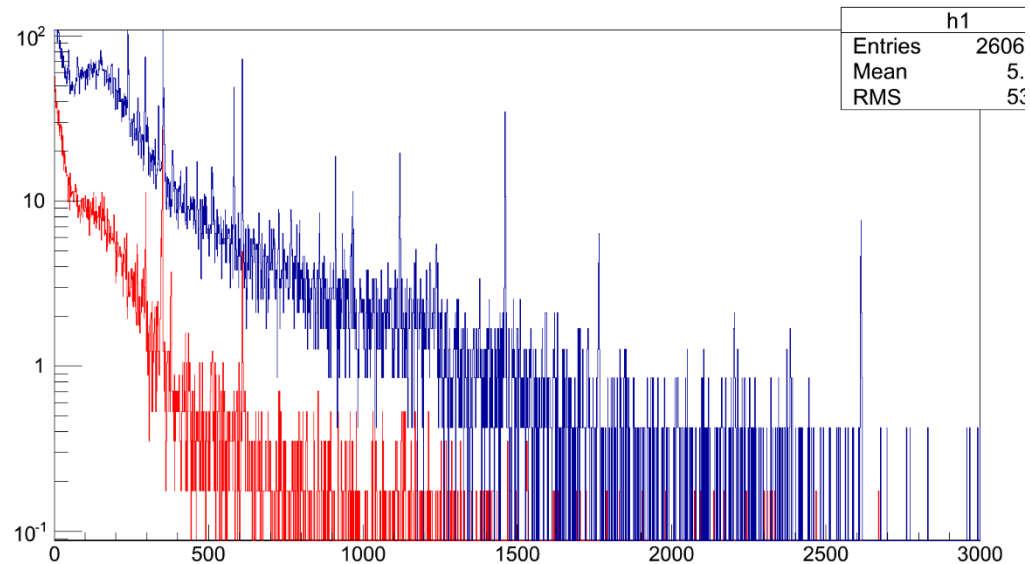
低噪声CMOS前放ASIC

- 2018年:
 - 采用0.35um CMOS工艺
 - 脉冲复位
 - 增益: 5-20 mV/fC
 - ENC噪声: 13.3 e @ 2pF, 77K, 26 e @ 0.5kg HPGe探测器

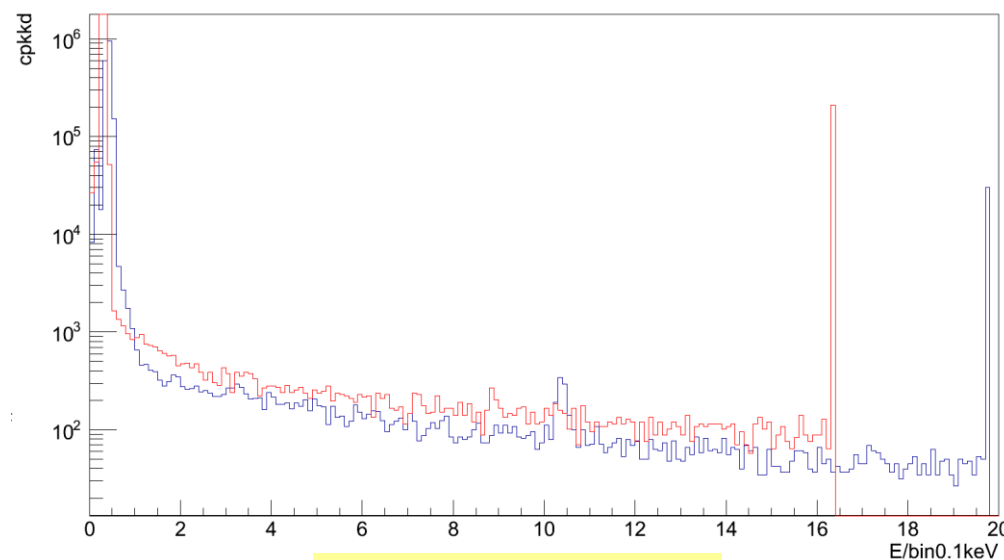


在 CDEX 实验中的应用

- 在CJPL开展的部分实验工作



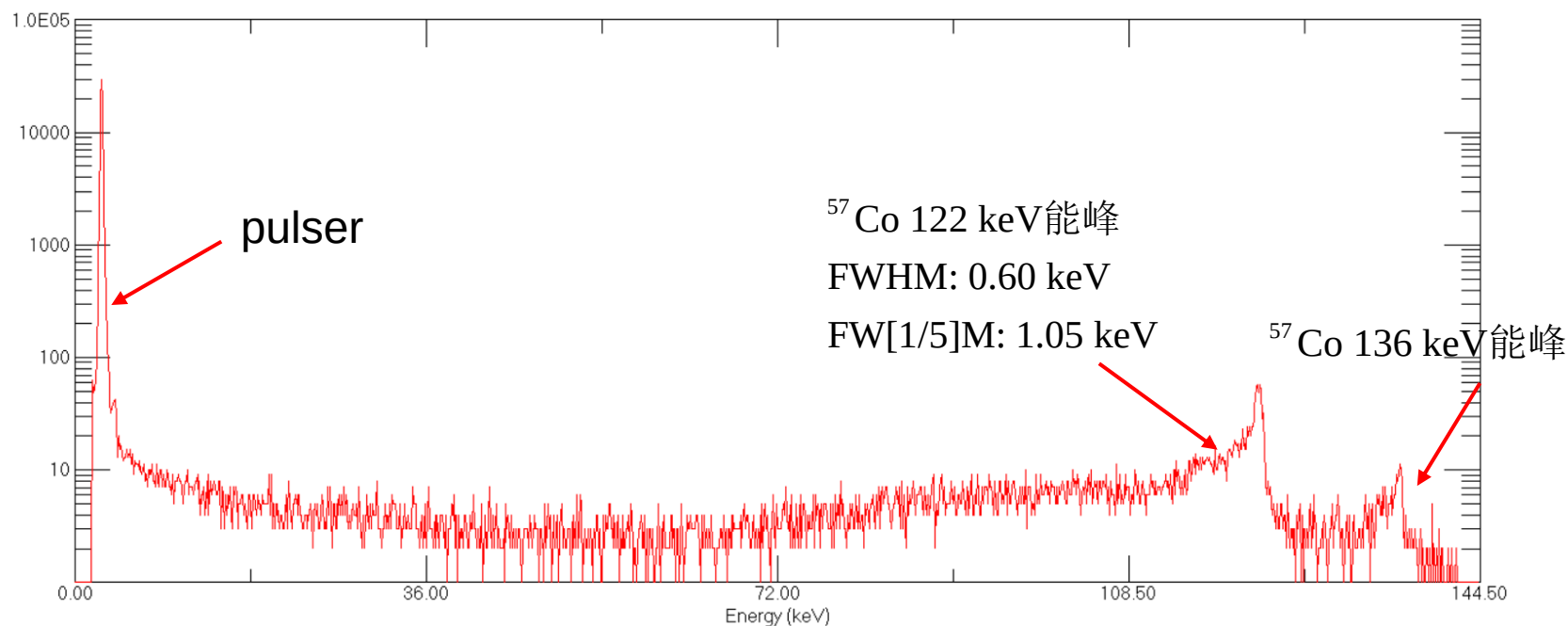
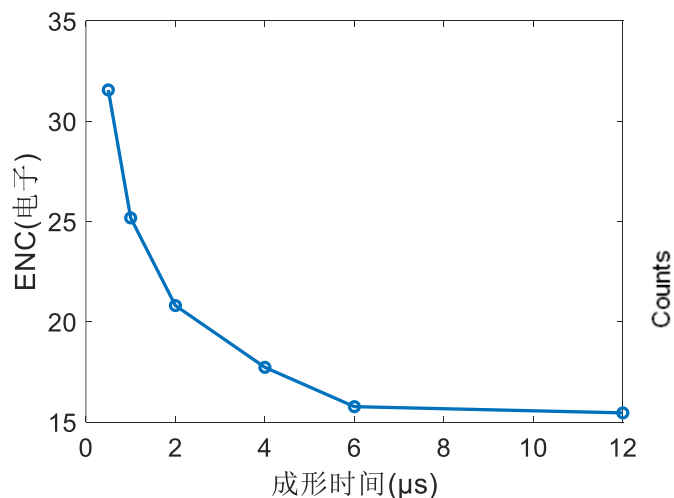
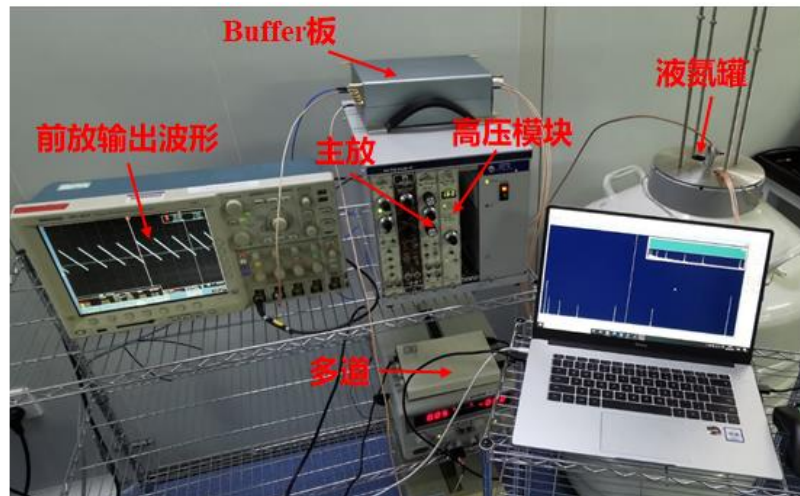
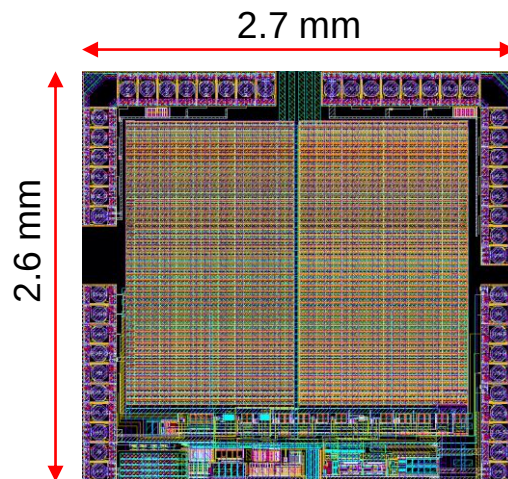
高能区本底分析



低能区本底分析

低噪声CMOS前放ASIC

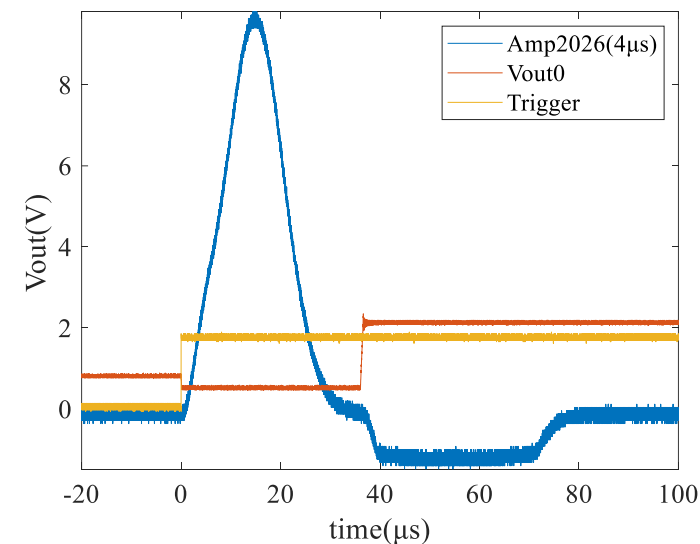
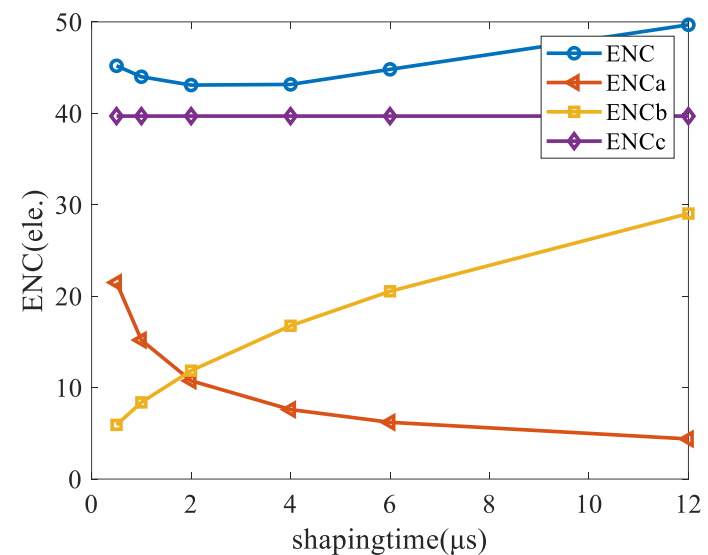
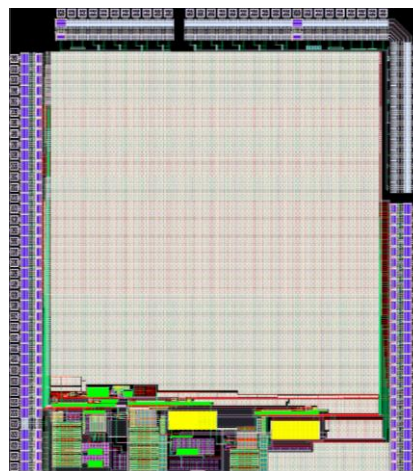
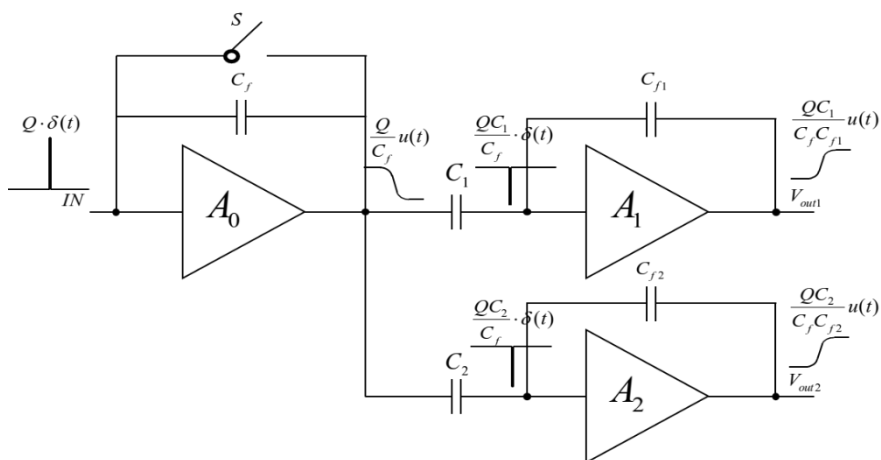
- 2021年
 - ENC=15.5 e @ 0.5kg HPGe, 目前CMOS前放ASIC连接大探测器的最好噪声结果



宽动态CMOS前放ASIC

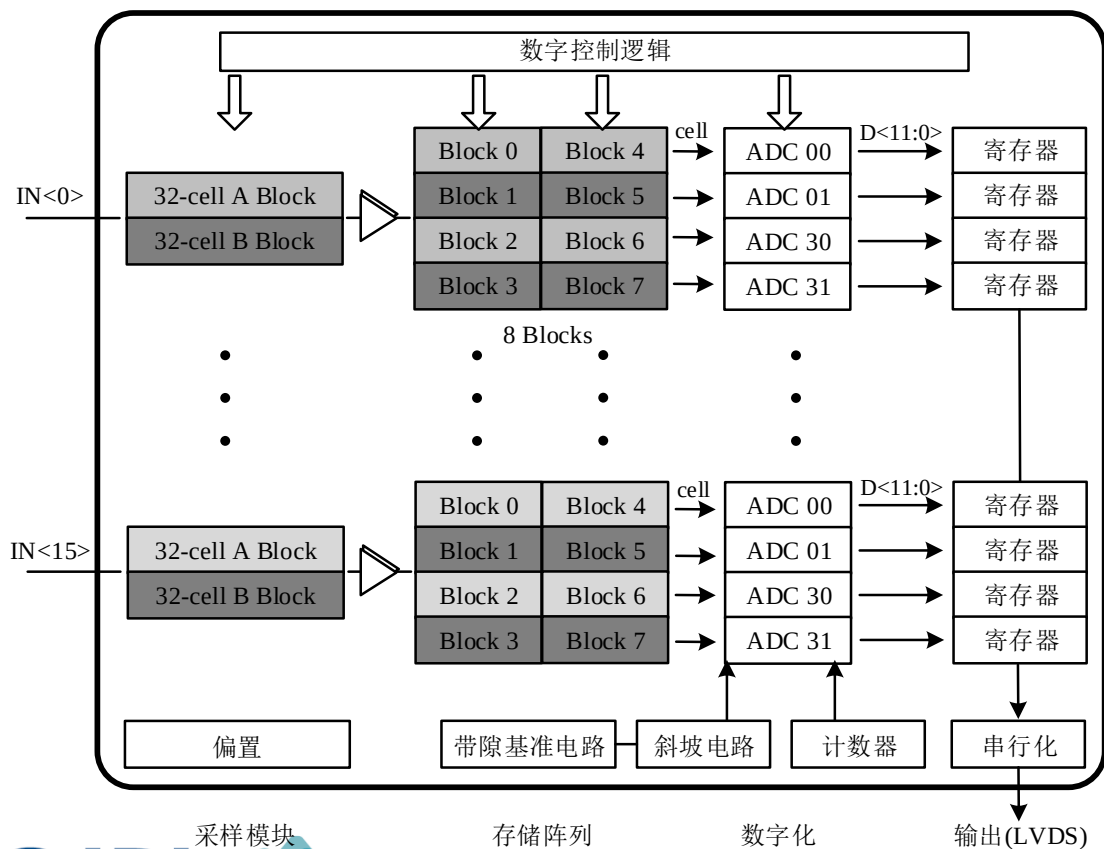
- 同时探测暗物质与无中微子双 β 衰变
 - 暗物质感能区: 0 - 20 keV
 - 无中微子双 β 衰变能区: 5 MeV
- 双增益+提前复位

DR >100000 : 1



低温SCA波形采样ASIC

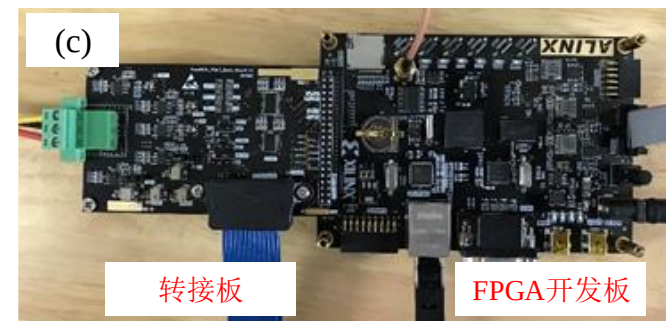
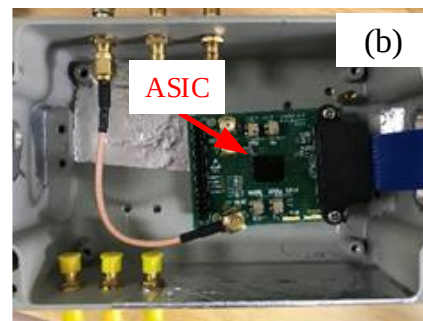
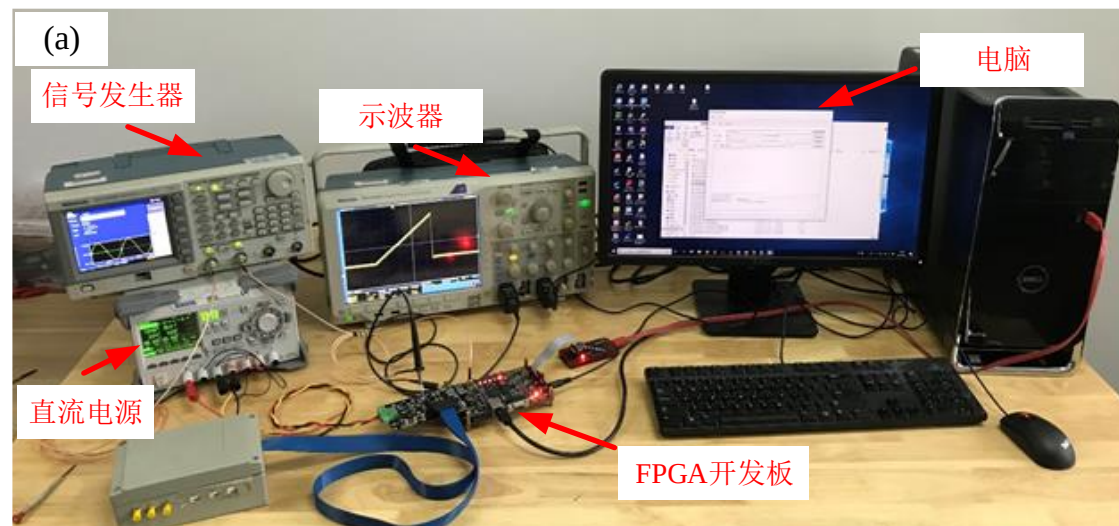
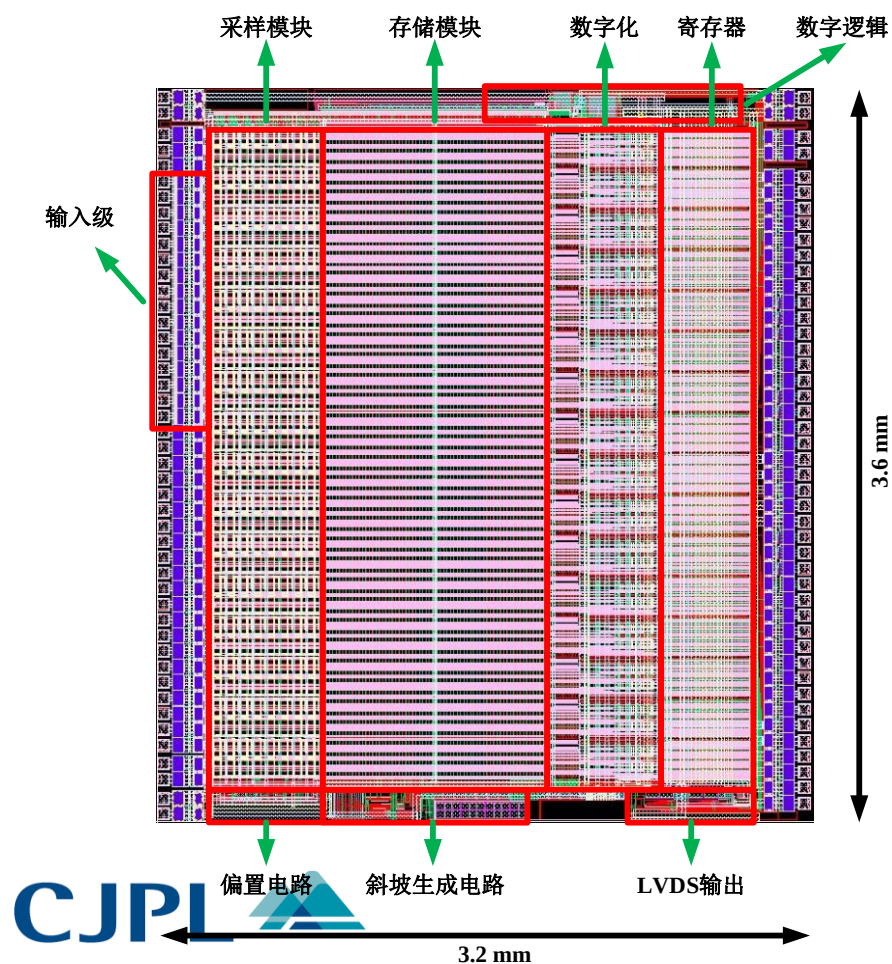
- 基于SCA（开关电容阵列）的波形采样芯片



参数	指标
工艺	0.18 μm CMOS 工艺
工作电压	1.8 V, 2.5 V
输入动态范围	0.3V - 1.3 V
采样频率	100 MS/s
采样深度	32 - 256
采样精度	> 10 bits
ADC时钟频率	100 MHz
ADC计数器	12 bits
ADC转换时间	42 μs
最大死时间	336 μs
核心功耗	3.2 mW/ch

低温SCA波形采样ASIC

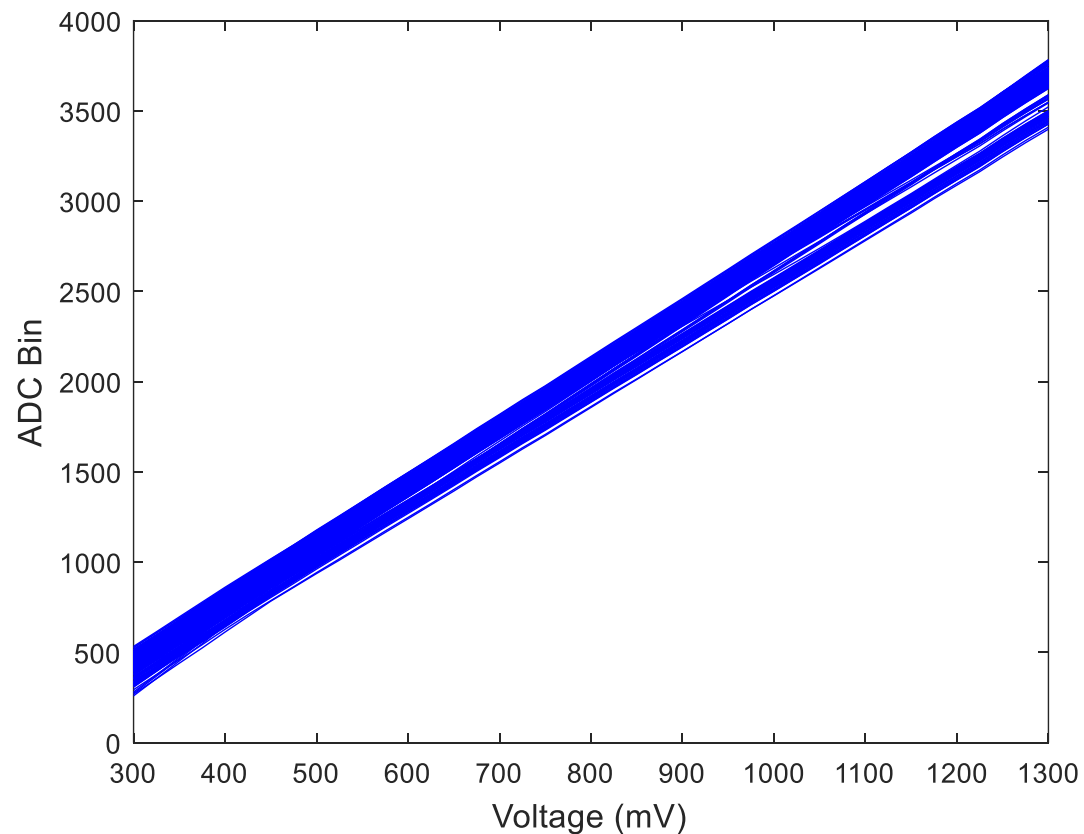
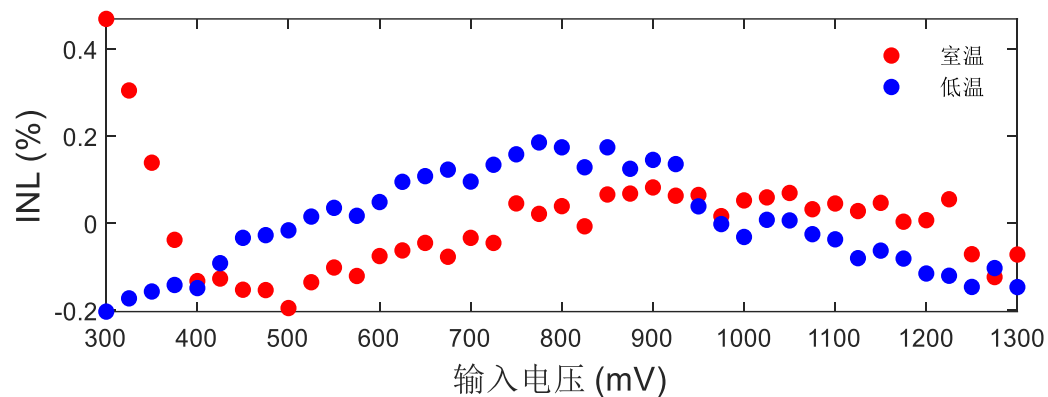
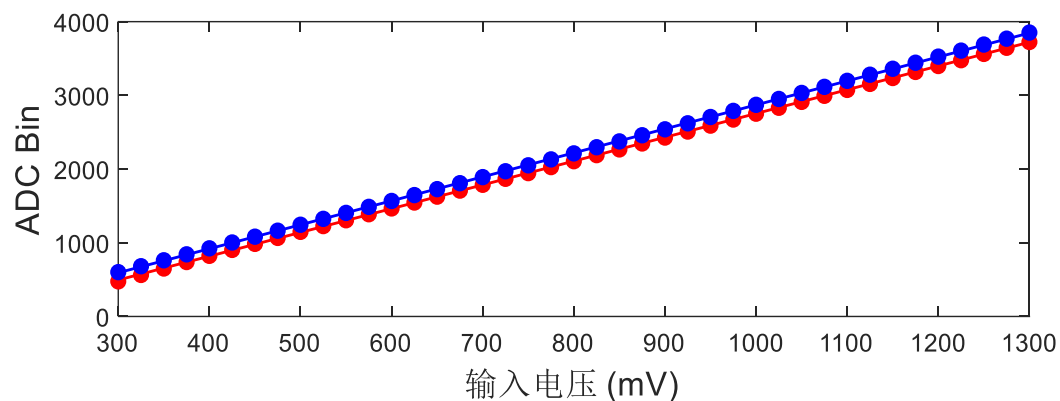
- 芯片版图和测试装置



低温SCA波形采样ASIC

- 积分非线性

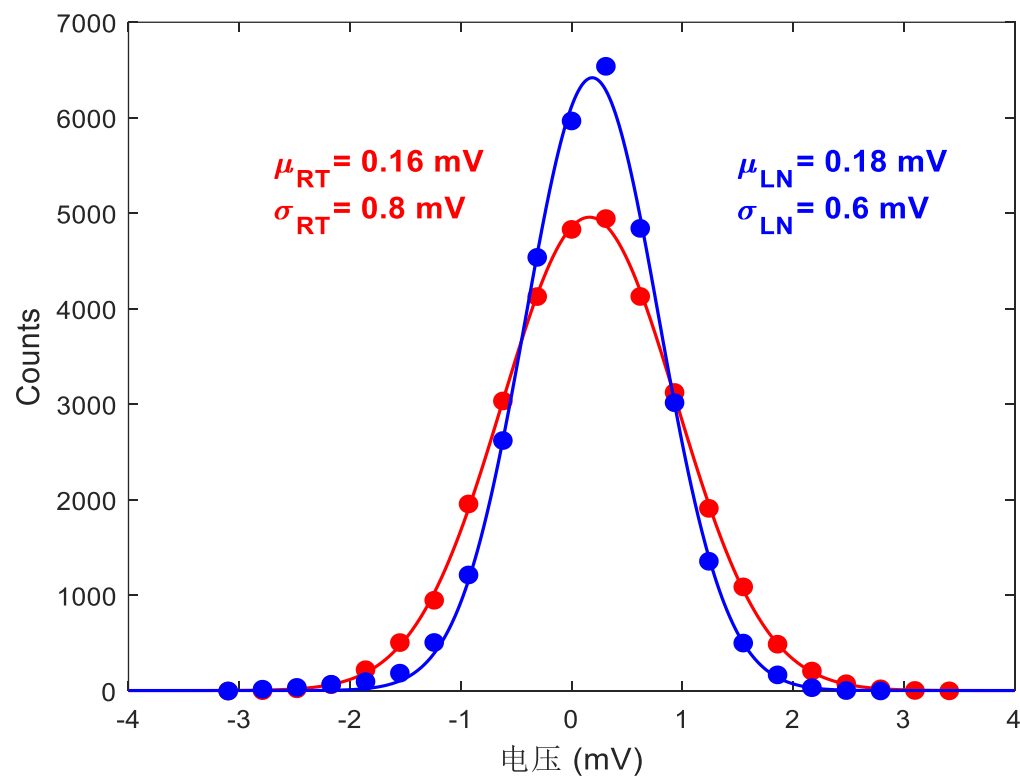
0.41% (室温) $\rightarrow$ 0.25% (低温)



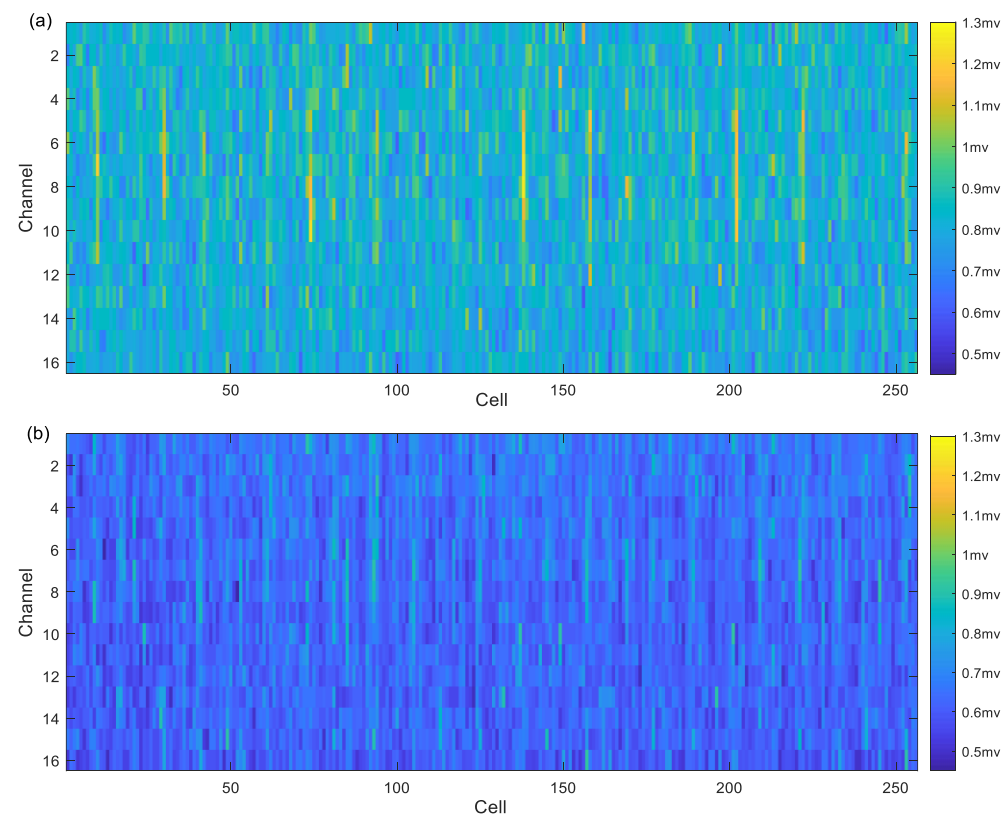
低温SCA波形采样ASIC

- 静态噪声性能

0.8 mV (室温) $\rightarrow$ 0.6 mV (低温)



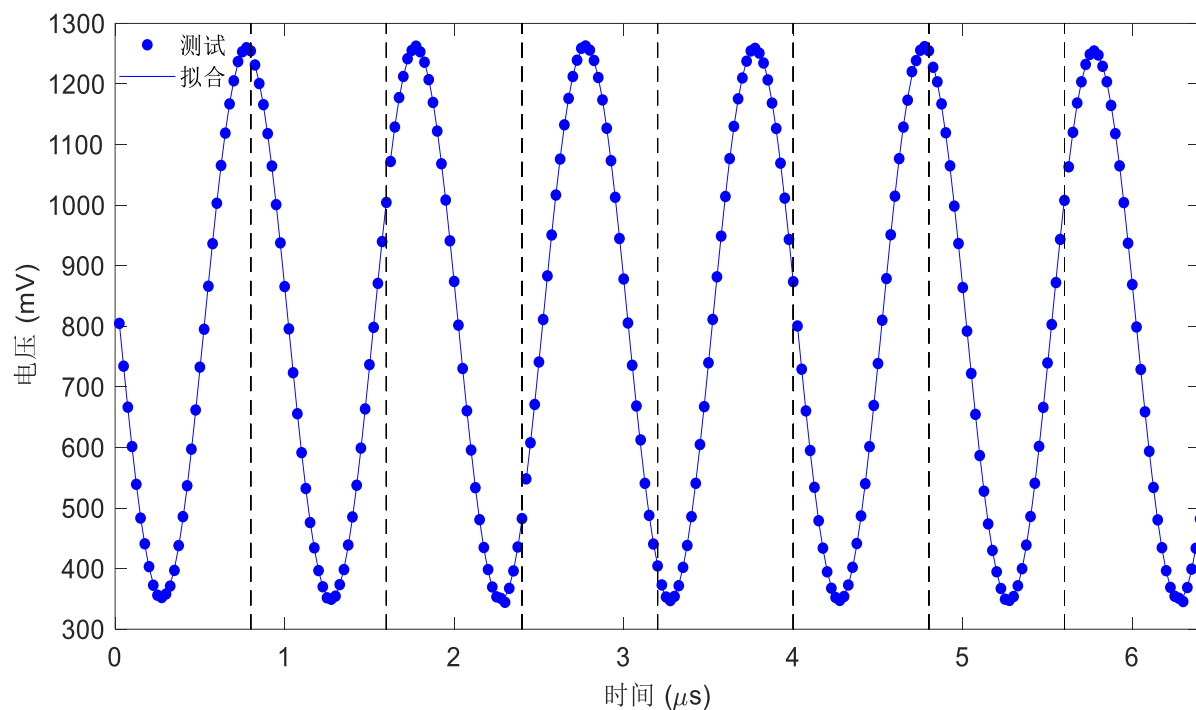
全芯片噪声分布较均匀



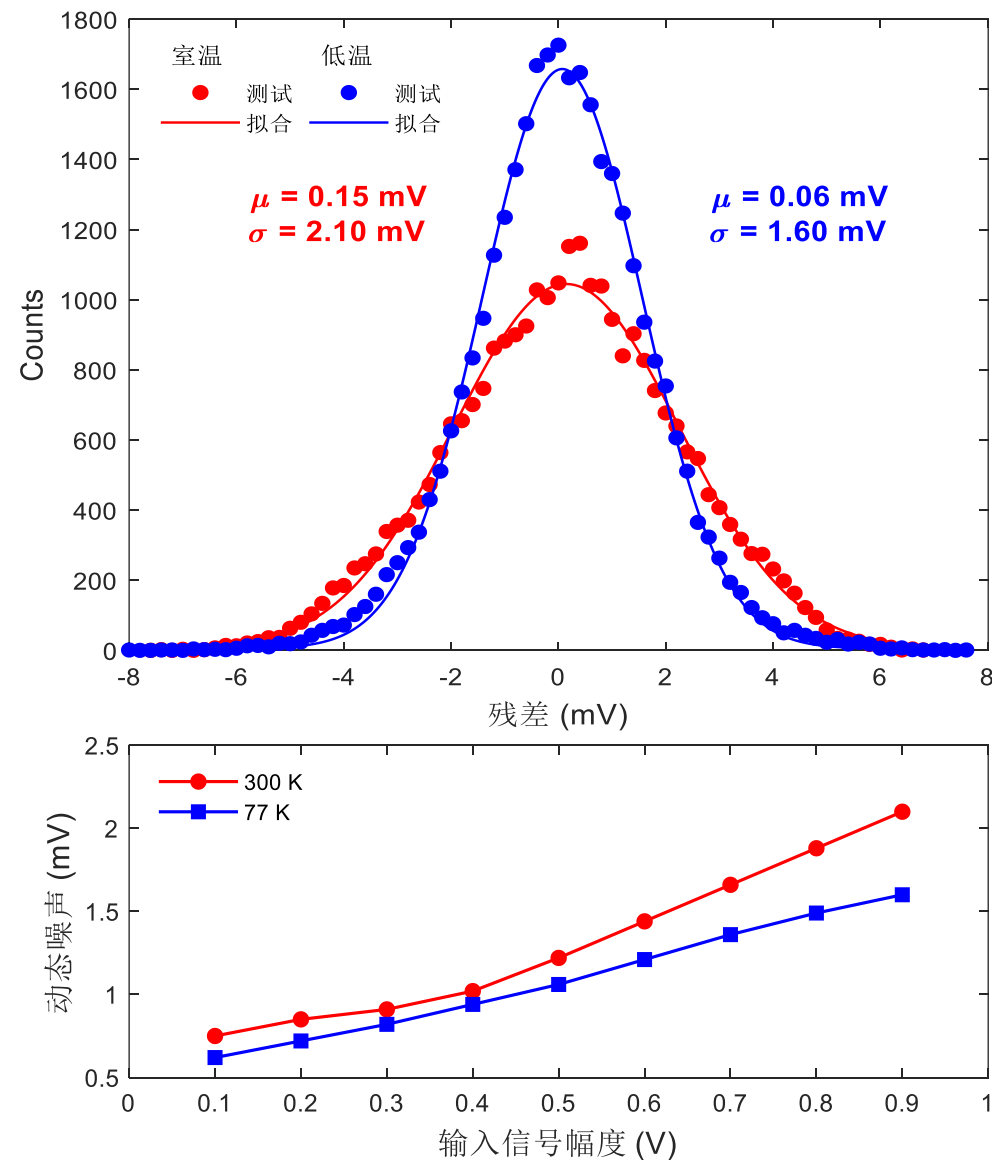
低温SCA波形采样ASIC

- 动态噪声性能

8.9 bits (室温) $\rightarrow$ 9.3 bits (低温)



低温40 MS/s连续采样经校准后的曲线



小结

- 目前完成的工作

- 补充低温（77K）下的CMOS仿真模型，根据该模型下设计出的电路仿真结果和实测结果误差 < 10%
- 设计完成多版前端低噪声ASIC，2018版ASIC已完成在锦屏的初步测试工作，2021版（本底更低）ASIC正在配合测试
- 能够同时应用于暗物质与 $0\nu\beta\beta$ 衰变实验中的宽动态范围ASIC完成了原理验证
- 低温SCA波形采样ASIC已完成基本性能测试

- 未来的工作计划

- 2021版（低本底版）ASIC配合完成CDEX相关实验验证工作；
- 完成宽动态范围ASIC的设计以及配合进行实验；
- 应用低温SCA波形采样ASIC到实验测试中；
- 更低噪声的ASIC设计：进一步降低 $1/f$ 噪声。